VIII. We Claim:

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A circuit board including:

h a base;

: a conductive layer adjacent to the base;

a dielectric material adjacent to conductive layer;

; a tooth structure including a metal layer set in the dielectric

material to join the dielectric material to the metal layer; and

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wherein the metal layer forms a portion of circuitry in a circuit board having multiple layers of circuitry.

2. The electrical device of claim 1, wherein the layers have a peal strength greater than the peel strength of a single desmear process.

3. The electrical device of claim 1, wherein the circuitry includes at least one micro via formed in the dielectric material.

4. The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 20% of the teeth are obtuse shaped.

- 5. The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 50% of the teeth are obtuse shaped.
- 6. The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 20% of the teeth are within the range of at least 1 tenth of a mil deep to 2 tenths of a mil deep.
- 7. The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 50% of the teeth are at least 1 tenth of a mil deep to 2 tenths of a mil deep.
- 8. The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 20% of the teeth are in the range of at least 1.5 tenths of a mil deep to 1.75 tenths of a mil deep.
- 9. The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 50% of the teeth are in the range of at least 1.5 tenths of a mil deep to 1.75 tenths of a mil deep.

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- The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 5,000 teeth per linear inch can be found.
- 11. The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 10,000 teeth per linear inch can be found.
- 12. The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 15,000 teeth per linear inch can be found.
- 13. The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 25,000 teeth per square inch can be found.
- 14. The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 100,000 teeth per square inch can be found.
- 15. The electrical device of claim 1, wherein the tooth structure includes teeth and in a sample of the electrical device, at least 200,000 teeth per square inch can be found.
- 16. The electrical device of claim 1, further including a second tooth structure that is not set in the dielectric material.
- 17. The electrical device of claim 1, further including a second tooth structure a tooth structure including the conductive layer set in the dielectric material to join the conductive layer to the dielectric material; wherein,

the second tooth structure formed by an oxide replacement process; and wherein

the electrical circuitry includes a connection through a micro via

- 18. The electrical device of claim 1, wherein the tooth structure is formed by a direct plate process.
- 19. The electrical device of claim 1, wherein the tooth structure is formed by a double desmear process.